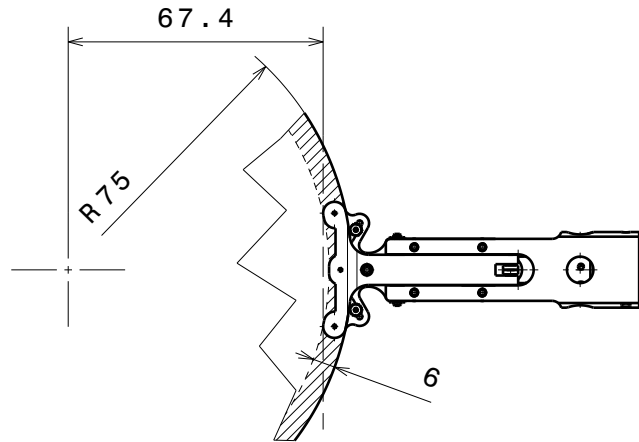


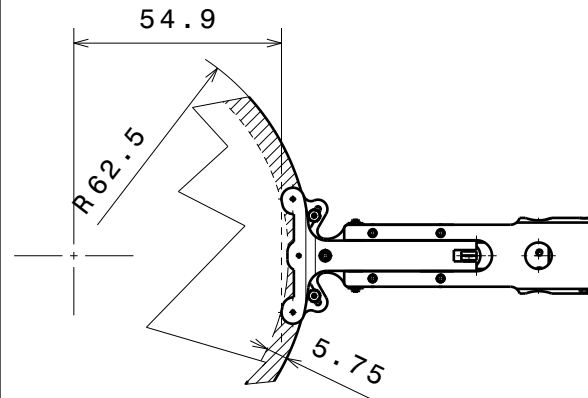
Material: fully UHV compatible	nominal ≤30mm	DIN ISO 2768-f-H
	dimensions >30mm	DIN ISO 2768-m-K excluding Sym./Runout
Straight Pincer High Force Version for Wafer	Sym./Runout >30mm	DIN ISO 2768-H
	formed part dimensions	DIN ISO 2768-f-H
PGHFMMWAF	Scale	Drawn C.Weiss
	1:1	Date
Rev. B		Changed
	Ferrovac GmbH CH-8050 Zurich	

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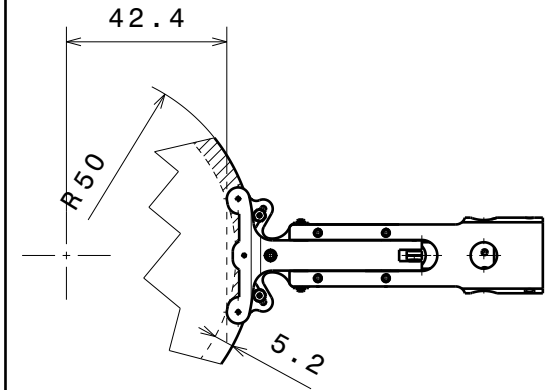
"6 inch Wafer



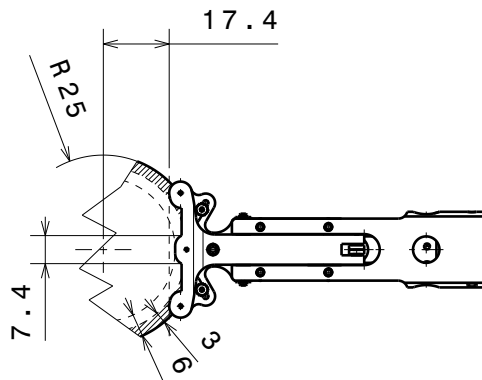
"4.9 inch Wafer



"4 inch Wafer



"2 inch Wafer



∇ Ra 0.8 (✓)
 \swarrow $\begin{matrix} +0.2 \\ +0.1 \end{matrix}$
 \searrow $\begin{matrix} -0.1 \\ -0.2 \end{matrix}$

Material: fully UHV compatible	nominal ≤ 30 mm dimensions > 30 mm	DIN ISO 2768-f-H DIN ISO 2768-m-K excluding Sym./Runout
Straight Pincer High Force Version for Wafer PGHFMMWAF	Sym./Runout > 30 mm formed part dimensions	DIN ISO 2768-H DIN ISO 2768-f-H
	Scale	Drawn C.Weiss Date 03.05.2018 Changed 28.01.2020 CW
Ferrovac GmbH CH-8050 Zurich	1:1	PGHFMMWAF
		A4 sheet 1/1
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